## Device Material Content

### Package: 208 FBGA | Package Code: FTG208 | MSL: 3

<table>
<thead>
<tr>
<th>Total Device Weight</th>
<th>0.750 Grams</th>
<th>Assembly: ASEK</th>
<th>Lead pitch (mm): 1.0</th>
<th>Rework max (ºC): 260</th>
</tr>
</thead>
</table>

### Products:
- **LPTM10**

<table>
<thead>
<tr>
<th>% of Subst.</th>
<th>Notes / Assumptions</th>
</tr>
</thead>
<tbody>
<tr>
<td>20.00%</td>
<td>Die: 3.25 x 3.25 mm + 2.65 x 2.65 mm Side-by-side (dual-die)</td>
</tr>
<tr>
<td>80.00%</td>
<td>Mold Compound: Kyocera G2250LKDS series (ULA)</td>
</tr>
<tr>
<td>8.00%</td>
<td>Die attach epoxy: Henkel (Ablebond) 2100A</td>
</tr>
</tbody>
</table>

### Notes / Assumptions:
- **Die**
  - Die size: 3.25 x 3.25 mm + 2.65 x 2.65 mm Side-by-side (dual-die)

**Mold Compound**

### Mold Compound

- **Silica**
- **Epoxy resin**
- **Phenol Resin**
- **Carbon Black**

### D/A Epoxy

- **Silicon chip**
- **Stainless steel**

### Wire

- **Gold (Au)**
- **Silver (Ag)**
- **Copper (Cu)**

### Solder Balls

- **Tin (Sn)**
- **Silver (Ag)**
- **Copper (Cu)**

### Substrate

- **BT Resin**
- **Glass fiber**

### Foil

- **Copper**
- **Nickel**
- **Gold**

### Solder Mask

- **Quartz**
- **3-methoxy-3-methylbutylacetate**
- **Barium Sulfate**
- **Talc (containing no asbestiform fibers)**
- **Trade secret ingredients**

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